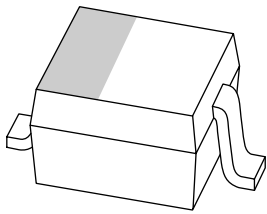


# DATA SHEET



**1PS76SB10**

Schottky barrier diode

Product data sheet  
Supersedes data of 1996 Oct 14

2004 Jan 26

# Schottky barrier diode

# 1PS76SB10

### FEATURES

- Low forward voltage
- Guard ring protected
- Very small plastic SMD package.

### APPLICATIONS

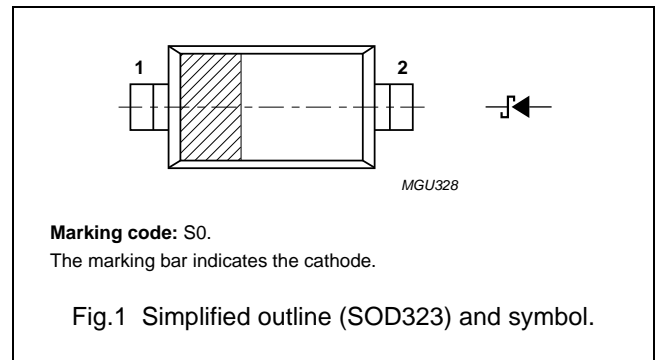
- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Blocking diodes.

### DESCRIPTION

Planar Schottky barrier diode encapsulated in a SOD323 very small plastic SMD package.

### PINNING

PIN	DESCRIPTION
1	cathode
2	anode



### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
1PS76SB10	–	plastic surface mounted package; 2 leads	SOD323

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_R$	continuous reverse voltage		–	30	V
$I_F$	continuous forward current		–	200	mA
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	–	300	mA
$I_{FSM}$	non-repetitive peak forward current	$t_p < 10$ ms	–	600	mA
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–	125	°C
$T_{amb}$	operating ambient temperature		–65	+125	°C

## Schottky barrier diode

1PS76SB10

**CHARACTERISTICS** $T_{amb} = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
$V_F$	forward voltage	see Fig.2		
		$I_F = 0.1\text{ mA}$	240	mV
		$I_F = 1\text{ mA}$	320	mV
		$I_F = 10\text{ mA}$	400	mV
		$I_F = 30\text{ mA}$	500	mV
		$I_F = 100\text{ mA}$	800	mV
$I_R$	reverse current	$V_R = 25\text{ V}$ ; note 1; see Fig.3	2	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1\text{ V}$ ; $f = 1\text{ MHz}$ ; see Fig.4	10	pF

**Note**1. Pulsed test:  $t_p = 300\text{ }\mu\text{s}$ ;  $\delta = 0.02$ .**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	450	K/W

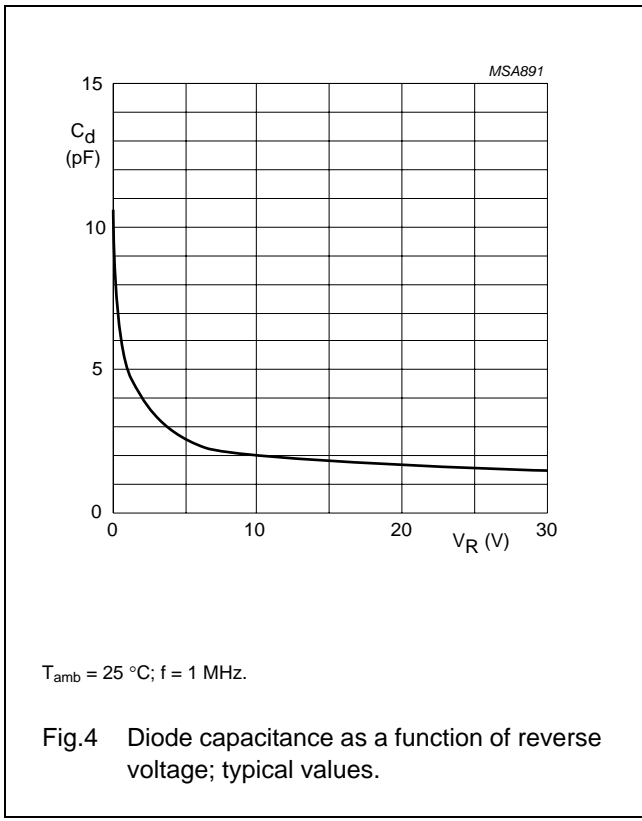
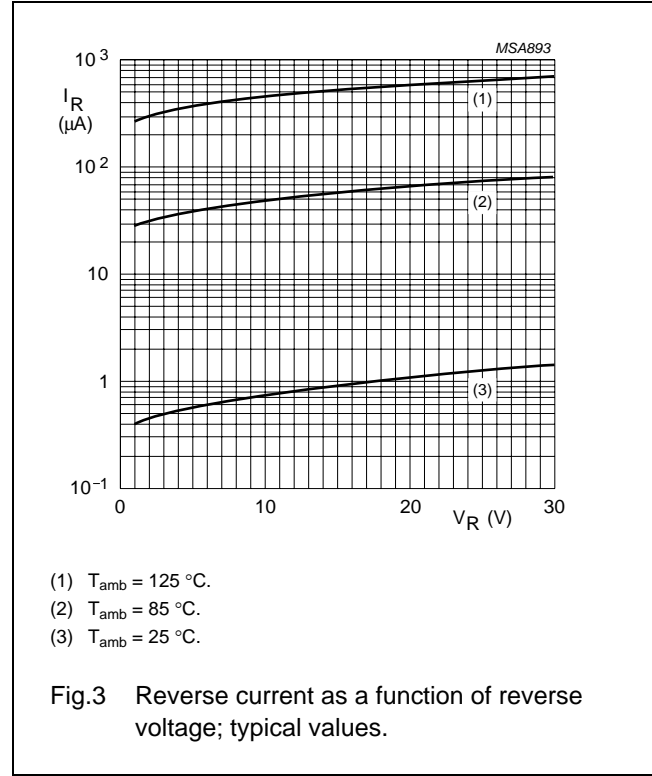
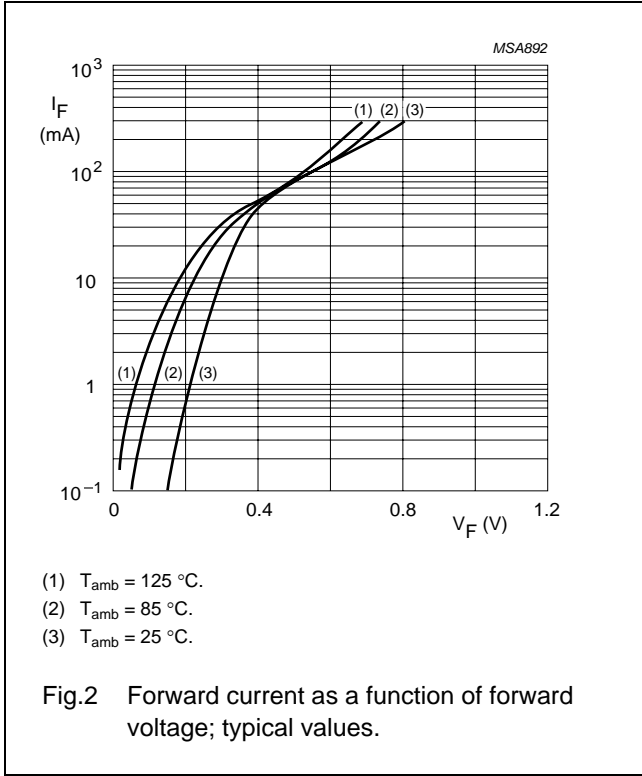
**Note**

1. Refer to SOD323 standard mounting conditions.

# Schottky barrier diode

# 1PS76SB10

## GRAPHICAL DATA



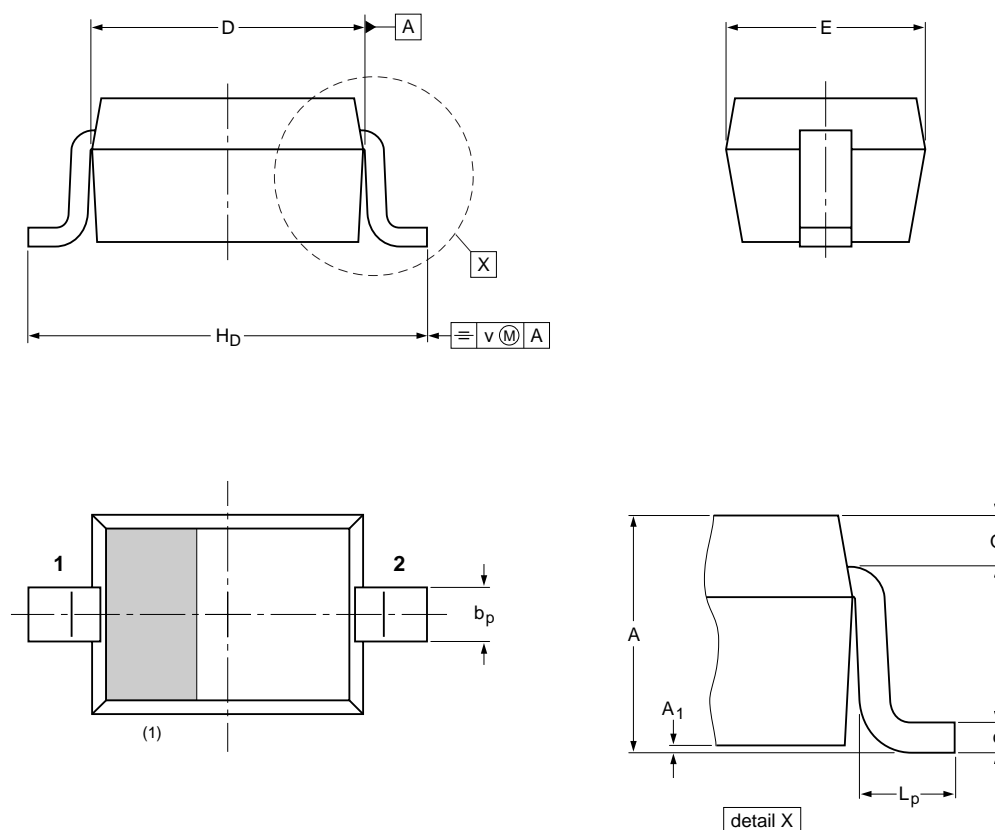
# Schottky barrier diode

# 1PS76SB10

## PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads

SOD323



**DIMENSIONS** (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	H <sub>D</sub>	L <sub>p</sub>	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

**Note**

1. The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOD323			SC-76		<del>03-12-17</del> 06-03-16

## Schottky barrier diode

1PS76SB10

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

## Notes

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## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

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